

Application No.: 10/565,565  
371(c) Date: January 23, 2006

### AMENDMENTS TO THE SPECIFICATION

Please amend Title as follows:

~~INORGANIC POWDER-CONTAINING RESIN COMPOSITION, FILM FORMING  
MATERIAL LAYER, TRANSFER SHEET, METHOD FOR PRODUCING SUBSTRATE  
WITH DIELECTRIC LAYER, AND SUBSTRATE WITH DIELECTRIC LAYER~~  
AN  
INORGANIC POWDER-CONTAINING RESIN COMPOSITION, A FILM-FORMING  
MATERIAL LAYER, A TRANSFER SHEET, METHOD OF PRODUCING A SUBSTRATE  
HAVING A DIELECTRIC LAYER FORMED THEREON, AND A SUBSTRATE HAVING A  
DIELECTRIC LAYER FORMED THEREON